

SNAS459A - MAY 2009 - REVISED APRIL 2013

# LM49200 Boomer® Audio Power Amplifier Series Stereo Class AB Audio Subsystem with a True Ground Headphone Amplifier

Check for Samples: LM49200, LM49200TLEVAL

#### **FEATURES**

- Differential Mono Input and Stereo Single-Ended Input
- 32-Step Digital Volume Control (-80 to +18dB)
- Three Independent Volume Channels (Left, Right, Mono)
- Separate Headphone Volume Control
- Flexible Output for Speaker and Headphone Output
- True Ground Headphone Amplifier Eliminates Large DC Blocking Capacitors Reducing PCB Space and Cost
- Receiver Pass-Through Capability
- Soft Enable Function
- RF Immunity Topology
- "Click and Pop" Suppression Circuitry
- Thermal Shutdown Protection
- Micro-Power Shutdown
- I<sup>2</sup>C Control Interface
- Available in Space-Saving DSBGA Package

#### **KEY SPECIFICATIONS**

- Supply Voltage (VDD): 2.7V ≤ VDD ≤ 5.5V
- I2C Supply Voltage: 1.7V ≤ I2CVDD ≤ 5.5V
- Output power at VDD = 5V, 1% THD+N
  - RL =  $8\Omega$  speaker: 1.25W (typ)
  - RL =  $32\Omega$  headphone: 38mW (typ)
- Output power at VDD = 3.3V, 1% THD+N
  - RL =  $8\Omega$  speaker: 520W (typ)
  - RL =  $32\Omega$  headphone: 38mW (typ)
- PSRR:
  - VDD = 3.3V, 217Hz ripple, Mono In: 95dB
  - (typ
- Shutdown power supply current 0.02μA (typ)

#### APPLICATIONS

- Portable Electronic Devices
- Mobile Phones
- PDAs

#### DESCRIPTION

The LM49200 is a fully integrated audio subsystem with a stereo power amplifier capable of delivering 500mW of continuous average power per channel into  $8\Omega$  with 1% THD+N using a 3.3V supply. The LM49200 includes a separate stereo headphone amplifier that can deliver 35mW per channel into  $32\Omega$ .

The LM49200 has three input channels. A pair of single-ended inputs and a fully differential input channel. The LM49200 features a 32-step digital volume control on the input stage and an 8-step digital volume control on the headphone output stage.

The digital volume control and output modes are programmed through a two-wire I<sup>2</sup>C compatible interface that allows flexibility in routing and mixing audio channels.

The LM49200 is designed for cellular phone, PDA, and other portable handheld applications. The high level of integration minimizes external components. The True Ground headphone amplifier eliminates the physically large DC blocking output capacitors reducing required board space and reducing cost.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



# **Typical Application**

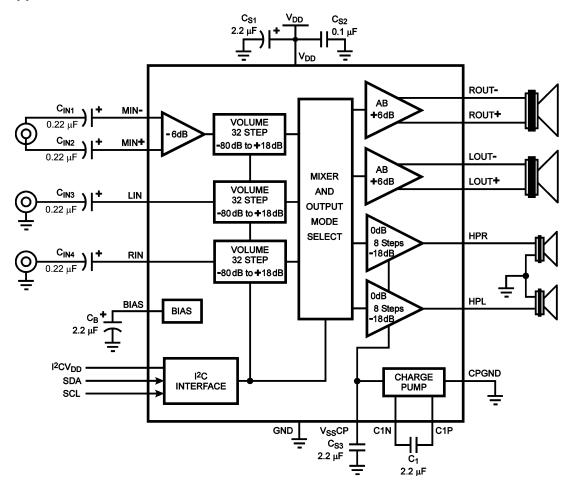


Figure 1. Typical Audio Application Circuit



# **Connection Diagram**

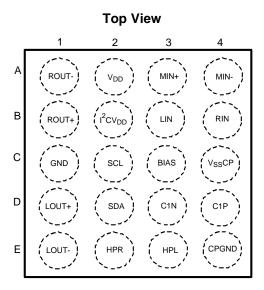


Figure 2. 20 Bump DSBGA Package (Bump Side Down) See Package Number YZR0020BBA

#### **Bump Descriptions**

Bump	Name	Pin Function	Туре
A1	ROUT-	Right Loudspeaker Negative Output	Analog Output
A2	VDD	Power Supply	Power Input
А3	MIN+	Differential Mono Positive Input	Analog Input
A4	MIN-	Differential Mono Negative Input	Analog Input
B1	ROUT+	Right Loudspeaker Positive Output	Analog Output
B2	I <sup>2</sup> CV <sub>DD</sub>	I <sup>2</sup> C power supply	Power Input
В3	LIN	Single-ended Left Input	Analog Input
B4	RIN	Single-ended Right Input	Analog Input
C1	GND	Power Ground	Ground
C2	SCL	I <sup>2</sup> C Clock	Digital Input
C3	BIAS	Half-Supply Bias point, capacitor bypassed	Analog Output
C4	VSSCP	Negative Charge Pump Power Supply	Analog Output
D1	LOUT+	Left Loudspeaker Negative Output	Analog Output
D2	SDA	I <sup>2</sup> C Data	Digital Input
D3	CIN	Negative Terminal Charge Pump Flying Capacitor	Analog Output
D4	CIP	Positive Terminal Charge Pump Flying Capacitor	Analog Output
E1	LOUT-	Left Loudspeaker Positive Output	Analog Output
E2	HPR	Right Headphone Output	Analog Output
E3	HPL	Left Headphone Output	Analog Output
E4	CPGND	Charge Pump Ground	Ground



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.



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# Absolute Maximum Ratings (1)(2)(3)

•		
Supply Voltage <sup>(1)</sup>		6.0V
Storage Temperature		−65°C to +150°C
Voltage at Any Input Pin		GND - 0.3 to V <sub>DD</sub> + 0.3V
Power Dissipation (4)		Internally Limited
ESD Rating <sup>(5)</sup>		2000V
ESD Rating <sup>(6)</sup>		200V
Junction Temperature (T <sub>JMAX</sub> )		150°C
Soldering Information	Vapor Phase (60sec.)	215°C
	Infrared (15sec.)	220°C
See AN-1112 "Micro SMD Wafer Leve	Chip Scale Package" (SNVA009).	
Thermal Resistance $\theta_{JA}$		45.1°C/W

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified
- (2) The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/ Distributors for availability and specifications.
- (4) The maximum power dissipation must be derated at elevated temperatures and is dictated by T<sub>JMAX</sub>, θ<sub>JA</sub>, and the ambient temperature, T<sub>A</sub>. The maximum allowable power dissipation is P<sub>DMAX</sub> = (T<sub>JMAX</sub> T<sub>A</sub>) / θ<sub>JA</sub> or the number given in *Absolute Maximum Ratings*, whichever is lower.
- (5) Human body model, applicable std. JESD22-A114C.
- (6) Machine model, applicable std. JESD22-A115-A.

#### **Operating Ratings**

Temperature Range T <sub>MIN</sub> ≤ T <sub>A</sub> ≤ T <sub>MAX</sub>	-40°C ≤ T <sub>A</sub> ≤ 85°C
Supply Voltage (V <sub>DD</sub> )	2.7V ≤ V <sub>DD</sub> ≤ 5.5V
Supply Voltage (I <sup>2</sup> CV <sub>DD</sub> )	$1.7V \le I^2CV_{DD} \le 5.5V$
	$I^2CV_{DD} \le V_{DD}$



# Electrical Characteristics $V_{DD} = 3.3V^{(1)(2)}$

The following specifications apply for  $V_{DD}$  = 3.3V,  $T_A$  = 25°C, all volume controls set to 0dB, unless otherwise specified. LS = Loudspeaker, HP = Headphone.

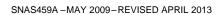
	Darameter	Test Conditions	LM <sup>2</sup>	LM49200			
	Parameter	Test Conditions	Typ <sup>(3)</sup>	Typ <sup>(3)</sup> Limits <sup>(4)</sup>			
		V <sub>IN</sub> = 0, No Loads					
		EP Receiver (Output Mode Bit D4 = 1)	1.2	1.7	mA (max)		
DD	Quiescent Power Supply Current	Stereo LS only (Mode 2)	4	5.5	mA (max)		
		Stereo HP only (Mode 8)	4.5	6.4	mA (max)		
		Stereo LS + Stereo HP (Mode 10)	7.0	9.8	mA (max)		
SD	Shutdown Current		0.02	1	μA (max)		
V <sub>os</sub>	Output Offset Voltage	$V_{IN}$ = 0V, Mode 10 LS output, R <sub>L</sub> = 8 $\Omega$ BTL HP output, R <sub>L</sub> = 32 $\Omega$ SE	2.5 1.4	15 5	mV (max) mV (max)		
<b>D</b> _	Output Power	LS output, Mode 2, $R_L = 8\Omega$ BTL THD+N = 1%, f = 1kHz	520	450	mW (min)		
Po	Output Fower	HP output, Mode 8, $R_L$ = 32Ω SE THD+N = 1%, f = 1kHz	38	35	mW (min)		
THD+N	Total Harmonic Distortion + Noise	LS output, f = 1kHz, $R_L = 8\Omega$ BTL $P_O = 250$ mW, Mode 2	0.05		%		
Total narmonic distortion + Noise		HP output, f = 1kHz, $R_L = 32\Omega$ SE $P_O = 12$ mW, Mode 8	0.02		%		
SNR	Circular Nation Parts	LS output, f = 1kHz, V <sub>REF</sub> = V <sub>OUT</sub> (1%THD+N) Gain = 0dB, A-weighted LIN & RIN AC terminated	105		dB		
	Signal-to-Noise Ratio	HP output, f = 1kHz,  V <sub>REF</sub> = V <sub>OUT</sub> (1%THD+N)  Gain = 0dB, A-weighted  LIN & RIN AC terminated	101		dB		
		A-weighted, Inputs terminated to AC GND, Output Referred					
		Right LS only, Mode 1	8		μV		
		LS: Mode 1	8		μV		
	Output Noise	LS: Mode 2	11		μV		
OUT	Output Noise	LS: Mode 3	14		μV		
		HP: Mode 4	8		μV		
		HP: Mode 8	9		μV		
		HP: Mode 12	11		μV		
		$V_{RIPPLE}$ = 200m $V_{PP}$ , $f_{RIPPLE}$ = 217Hz, $C_B$ = 2.2 $\mu$ F All inputs AC terminated to GND, output referred					
2005		LS: Mode 1, R <sub>L</sub> = 8Ω BTL			dB		
PSRR	Power Supply Rejection Ratio	LS: Mode 2, $R_L = 8\Omega$ BTL	75		dB		
		HP: Mode 4, $R_L = 32\Omega$ SE	90		dB		
		HP: Mode 8, $R_L = 32Ω$ SE	80		dB		

<sup>(1) &</sup>quot;Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified

<sup>(2)</sup> The Electrical Characteristics tables list ensured specifications under the listed Recommended Operating Conditions except as otherwise modified or specified by the Electrical Characteristics Conditions and/or Notes. Typical specifications are estimations only and are not ensured.

<sup>(3)</sup> Typical values represent most likely parametric norms at T<sub>A</sub> = +25°C, and at the *Recommended Operation Conditions* at the time of product characterization and are not ensured.

<sup>(4)</sup> Datasheet min/max specification limits are ensured by test or statistical analysis.





# Electrical Characteristics $V_{DD} = 3.3V^{(1)(2)}$ (continued)

The following specifications apply for  $V_{DD}$  = 3.3V,  $T_A$  = 25°C, all volume controls set to 0dB, unless otherwise specified. LS = Loudspeaker, HP = Headphone.

	D	Total Constitions	LM4	Units	
Parameter		Test Conditions	Typ <sup>(3)</sup>	Limits <sup>(4)</sup>	(Limits)
CMRR	Common-Mode Rejection Ratio	$ f = 217 \text{Hz},  V_{\text{CM}} = 1 V_{\text{P-P}} \\ \text{LS: } R_{\text{L}} = 8 \Omega  \text{BTL},  \text{Mode 1} \\ \text{HP: } R_{\text{L}} = 32 \Omega  \text{SE},  \text{Mode 4} $	60 66		dB dB
V	X <sub>TALK</sub> Crosstalk	LS: P <sub>O</sub> = 400mW, f = 1kHz, Mode 2	80		dB
<b>A</b> TALK		HP: P <sub>O</sub> = 12mW, f = 1kHz, Mode 8	70		dB
7		Maximum Gain setting	12.5	10 15	kΩ (min) kΩ (max)
Z <sub>IN</sub> MIN, LIN, and RIN Input Impedance	Maximum Attenuation setting	110	90 130	kΩ (min) kΩ (max)	
VOL	Digital Volume Control Range	Maximum Gain Maximum Attenuation	18 -80		dB dB
VOL	Volume Control Step Size Error		0.2		dB
-	Wake I in Time from Shutdown	C <sub>B</sub> = 2.2μF, HP, Normal Turn-On Mode	29		ms
T <sub>WU</sub> Wak	Wake-Up Time from Shutdown	C <sub>B</sub> = 2.2µF, HP, Fast Turn-On Mode	16		ms

# Electrical Characteristics $V_{DD} = 5.0V^{(1)(2)}$

The following specifications apply for  $V_{DD}$  = 5.0V,  $T_A$  = 25°C, all volume controls set to 0dB, unless otherwise specified. LS = Loudspeaker, HP = Headphone.

		T . O . III	LM4	LM49200		
Parameter		Test Conditions	Typ <sup>(3)</sup>	Limits <sup>(4)</sup>	(Limits)	
		V <sub>IN</sub> = 0, No Loads				
		EP Receiver (Output Mode Bit D4 = 1)	1.3	1.8	mA (max)	
$I_{DD}$	Quiescent Power Supply Current	Stereo LS only (Mode 2)	4.2	5.9	mA (max)	
		Stereo HP only (Mode 8)	4.7	6.5	mA (max)	
		Stereo LS + Stereo HP (Mode 10)	7.3	10.1	mA (max)	
I <sub>SD</sub>	Shutdown Current		0.02	1	μA (max)	
Vos	Output Offset Voltage	$V_{\text{IN}} = 0V$ , Mode 10 LS output, $R_{\text{L}} = 8\Omega$ BTL HP output, $R_{\text{L}} = 32\Omega$ SE	2.5 1.4	15 5	mV (max) mV (max)	
<b>D</b>		LS output, Mode 2, $R_L = 8\Omega$ BTL THD+N = 1%, f = 1kHz	1.25		W	
P <sub>O</sub> Out	Output Power	HP output, Mode 8, $R_L = 32Ω$ SE THD+N = 1%, $f = 1kHz$	38		mW	
THD+N	Total Harmonia Distortion - Naise	LS output, f = 1kHz, $R_L = 8\Omega$ BTL $P_O = 400$ mW, Mode 2	0.05		%	
	Total Harmonic Distortion + Noise	HP output, f = 1kHz, $R_L = 32Ω$ SE $P_O = 12mW$ , Mode 8	0.02		%	

<sup>(1) &</sup>quot;Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur, including inoperability and degradation of device reliability and/or performance. Functional operation of the device and/or non-degradation at the Absolute Maximum Ratings or other conditions beyond those indicated in the Recommended Operating Conditions is not implied. The Recommended Operating Conditions indicate conditions at which the device is functional and the device should not be operated beyond such conditions. All voltages are measured with respect to the ground pin, unless otherwise specified

<sup>(2)</sup> The *Electrical Characteristics* tables list ensured specifications under the listed *Recommended Operating Conditions* except as otherwise modified or specified by the *Electrical Characteristics Conditions* and/or Notes. Typical specifications are estimations only and are not ensured.

<sup>(3)</sup> Typical values represent most likely parametric norms at T<sub>A</sub> = +25°C, and at the *Recommended Operation Conditions* at the time of product characterization and are not ensured.

<sup>(4)</sup> Datasheet min/max specification limits are ensured by test or statistical analysis.



# Electrical Characteristics $V_{DD} = 5.0V^{(1)(2)}$ (continued)

The following specifications apply for  $V_{DD}$  = 5.0V,  $T_A$  = 25°C, all volume controls set to 0dB, unless otherwise specified. LS = Loudspeaker, HP = Headphone.

	Danamatan.	Took Conditions	LM49200		Units (Limits)		
	Parameter	Test Conditions	Typ <sup>(3)</sup> Limits <sup>(4)</sup>				
SNR	Cinnel to Naiga Datio	LS output, f = 1kHz, V <sub>REF</sub> = V <sub>OUT</sub> (1%THD+N) Gain = 0dB, A-weighted LIN & RIN AC terminated	109		dB		
SINK	Signal-to-Noise Ratio	HP output, f = 1kHz, V <sub>REF</sub> = V <sub>OUT</sub> (1%THD+N) Gain = 0dB, A-weighted LIN & RIN AC terminated	101		dB		
		A-weighted, Inputs terminated to AC GND, O	utput Referred	d			
		Right LS only, Mode 1	8		μV		
		LS: Mode 1	8		μV		
_	Output Naina	LS: Mode 2	11		μV		
OUT	Output Noise	LS: Mode 3	14		μV		
		HP: Mode 4	8		μV		
		HP: Mode 8	9		μV		
		HP: Mode 12	11		μV		
		V <sub>RIPPLE</sub> = 200mV <sub>P-P</sub> , f <sub>RIPPLE</sub> = 217Hz, C <sub>B</sub> = 2.2μF All inputs AC terminated to GND, output referred					
	Power Supply Rejection Ratio	LS: Mode 1, $R_L = 8\Omega$ BTL	90		dB		
PSRR		LS: Mode 2, $R_L = 8\Omega$ BTL	70		dB		
		HP: Mode 4, $R_L = 32Ω$ SE	87		dB		
		HP: Mode 8, $R_L = 32Ω$ SE	77		dB		
CMRR	Common-Mode Rejection Ratio	$f$ = 217Hz, $V_{CM}$ = 1 $V_{P-P}$ LS: $R_L$ = 8 $\Omega$ BTL, Mode 1 HP: $R_L$ = 32 $\Omega$ SE, Mode 4	60 66		dB dB		
	Consistent.	LS: P <sub>O</sub> = 1W, f = 1kHz, Mode 2	80		dB		
X <sub>TALK</sub>	Crosstalk	HP: P <sub>O</sub> = 12mW, f = 1kHz, Mode 8	70		dB		
7	MINI LINE and DIN languation of the control of the	Maximum Gain setting	12.5		kΩ		
ZIN	MIN, LIN, and RIN Input Impedance	Maximum Attenuation setting	110		kΩ		
/OL	Digital Volume Control Range	Maximum Gain Maximum Attenuation	18 -80		dB dB		
/OL	Volume Control Step Size Error		0.2		dB		
T <sub>WU</sub>	Wake-Up Time from Shutdown	C <sub>B</sub> = 2.2µF, HP, Normal Turn-On Mode			ms		
' WU	wake op tille holl ollulowii	C <sub>B</sub> = 2.2µF, HP, Fast Turn-On Mode	16		ms		

Product Folder Links: LM49200 LM49200TLEVAL



# I<sup>2</sup>C Interface<sup>(1)(2)</sup>

The following specifications apply for  $V_{DD} = 5.0 \text{V}$  and 3.3V,  $2.2 \text{V} \leq \text{I}^2 \text{C}_{-} \text{V}_{DD} \leq 5.5 \text{V}$ ,  $\text{T}_{A} = 25 ^{\circ} \text{C}$ , unless otherwise specified.

	Parameter Test Conditions		1	LM49200	Units
	Parameter	rest Conditions	Typ <sup>(3)</sup>	Limits <sup>(4)(5)</sup>	(Limits)
t <sub>1</sub>	I <sup>2</sup> C Clock Period			2.5	μs (min)
t <sub>2</sub>	I <sup>2</sup> C Data Setup Time			100	ns (min)
t <sub>3</sub>	I <sup>2</sup> C Data Stable Time			0	ns (min)
t <sub>4</sub>	Start Condition Time			100	ns (min)
t <sub>5</sub>	Stop Condition Time			100	ns (min)
t <sub>6</sub>	I <sup>2</sup> C Data Hold Time			100	ns (min)
V <sub>IH</sub>	I <sup>2</sup> C Input Voltage High			0.7xl <sup>2</sup> CV <sub>DD</sub>	V (min)
V <sub>IL</sub>	I <sup>2</sup> C Input Voltage Low			0.3xl <sup>2</sup> CV <sub>DD</sub>	V (max)

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- (3) Human body model, applicable std. JESD22-A114C.
- (4) Datasheet min/max specification limits are ensured by test or statistical analysis.
- (5) Refer to the I<sup>2</sup>C timing diagram, Figure 32.

# I<sup>2</sup>C Interface<sup>(1)(2)</sup>

The following specifications apply for  $V_{DD} = 5.0V$  and 3.3V,  $1.7V \le I^2C_{-}V_{DD} \le 2.2V$ ,  $T_A = 25^{\circ}C$ , unless otherwise specified.

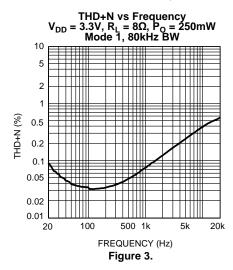
	Parameter Test Conditions			LM49200	Units
	Parameter	Test Conditions	Typ <sup>(3)</sup>	Limits <sup>(4) (5)</sup>	(Limits)
t <sub>1</sub>	I <sup>2</sup> C Clock Period			2.5	μs (min)
t <sub>2</sub>	I <sup>2</sup> C Data Setup Time			250	ns (min)
t <sub>3</sub>	I <sup>2</sup> C Data Stable Time			0	ns (min)
t <sub>4</sub>	Start Condition Time			250	ns (min)
t <sub>5</sub>	Stop Condition Time			250	ns (min)
t <sub>6</sub>	I <sup>2</sup> C Data Hold Time			250	ns (min)
V <sub>IH</sub>	I <sup>2</sup> C Input Voltage High			0.7xl <sup>2</sup> CV <sub>DD</sub>	V (min)
V <sub>IL</sub>	I <sup>2</sup> C Input Voltage Low			0.3xl <sup>2</sup> CV <sub>DD</sub>	V (max)

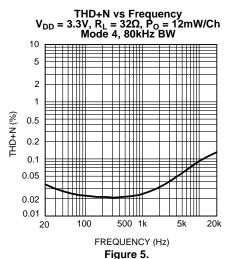
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- (3) Typical values represent most likely parametric norms at T<sub>A</sub> = +25°C, and at the Recommended Operation Conditions at the time of product characterization and are not ensured.
- (4) Datasheet min/max specification limits are ensured by test or statistical analysis.
- (5) Refer to the I<sup>2</sup>C timing diagram, Figure 32.

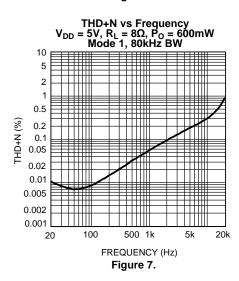


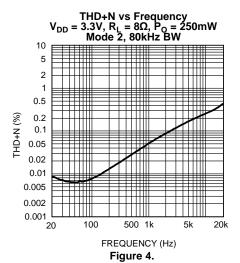
#### **Typical Performance Characteristics**

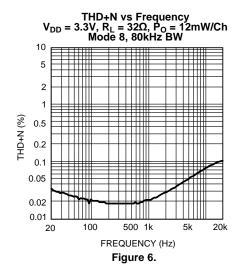
For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

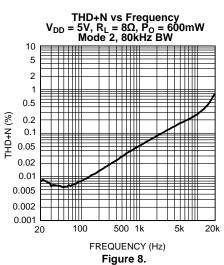






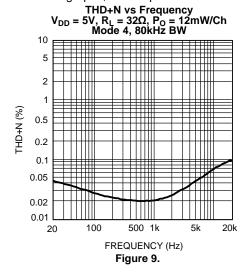


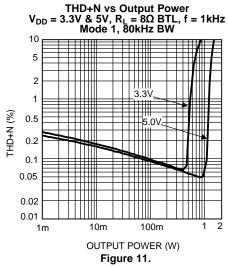


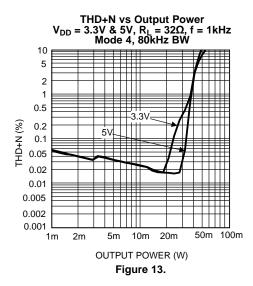


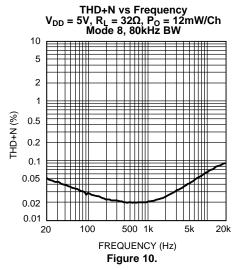


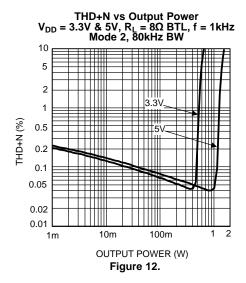
For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

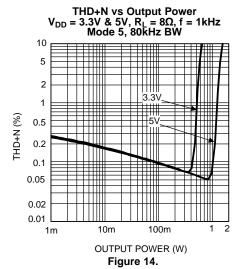






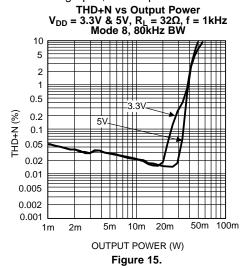


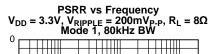


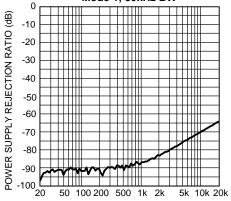




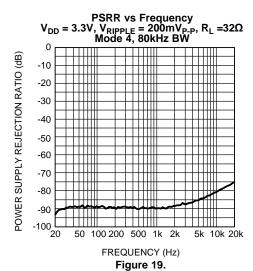
For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

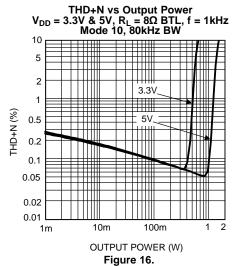


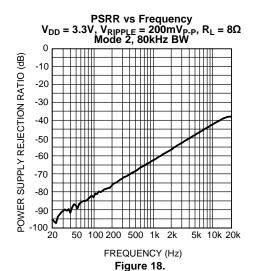




FREQUENCY (Hz) Figure 17.







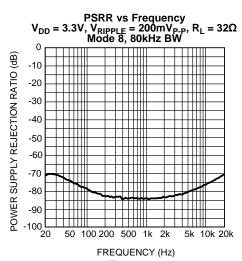
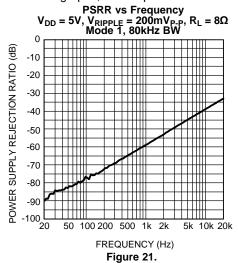
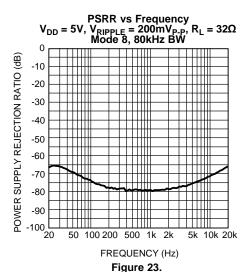


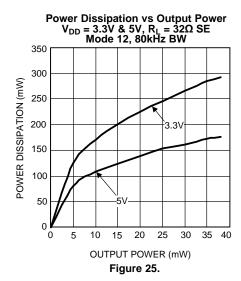
Figure 20.

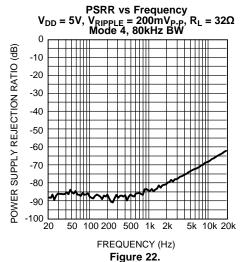


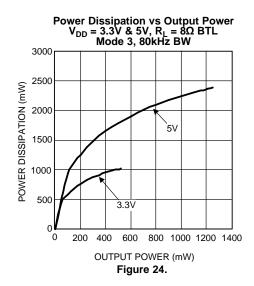
For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.

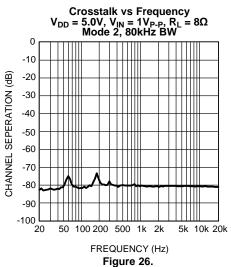






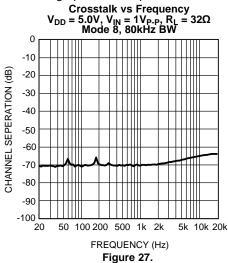








For all performance graphs, the Output Gains are set to 0dB, unless otherwise noted.



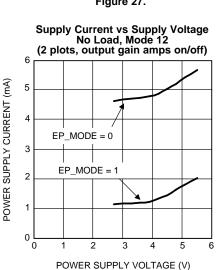
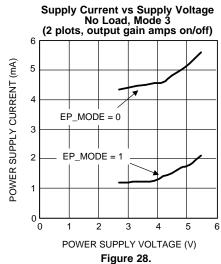
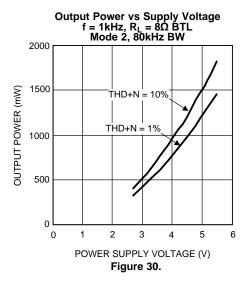
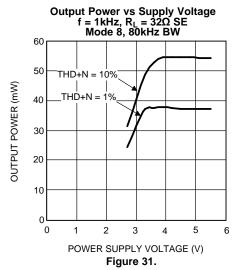


Figure 29.









#### **APPLICATION INFORMATION**

#### I<sup>2</sup>C COMPATIBLE INTERFACE

The LM49200 is controlled through an I<sup>2</sup>C compatible serial interface that consists of a serial data line (SDA) and a serial clock (SCL). The clock line is uni-directional. The data line is bi-directional (open drain). The LM49200 and the master can communicate at clock rates up to 400kHz. Figure 32 shows the I<sup>2</sup>C interface timing diagram. Data on the SDA line must be stable during the HIGH period of SCL. The LM49200 is a transmit/receive slave-only device, reliant upon the master to generate the SCL signal. Each transmission sequence is framed by a START condition and a STOP condition (Figure 33). Each data word, device address and data, transmitted over the bus is 8 bits long and is always followed by an acknowledge pulse (Figure 34). The LM49200 device address is 11111000.

# I<sup>2</sup>C INTERFACE POWER SUPPLY PIN (I<sup>2</sup>CV<sub>DD</sub>)

The LM49200's I<sup>2</sup>C interface is powered up through the I<sup>2</sup>CV<sub>DD</sub> pin. The LM49200's I<sup>2</sup>C interface operates at a voltage level set by the I<sup>2</sup>CV<sub>DD</sub> pin which can be set independent to that of the main power supply pin V<sub>DD</sub>. This is ideal whenever logic levels for the I<sup>2</sup>C interface are dictated by a microcontroller or microprocessor that is operating at a lower supply voltage than the main battery of a portable system

#### I<sup>2</sup>C BUS FORMAT

The I<sup>2</sup>C bus format is shown in Figure 34. The START signal, the transition of SDA from HIGH to LOW while SCL is HIGH, is generated, alerting all devices on the bus that a device address is being written to the bus.

The 7-bit device address is written to the bus, most significant bit (MSB) first, followed by the  $R/\overline{W}$  bit.  $R/\overline{W}=0$  indicates the master is writing to the slave device,  $R/\overline{W}=1$  indicates the master wants to read data from the slave device. Set  $R/\overline{W}=0$ ; the LM49200 is a WRITE-ONLY device and will not respond to the  $R/\overline{W}=1$ . The data is latched in on the rising edge of the clock. Each address bit must be stable while SCL is HIGH. After the last address bit is transmitted, the master device releases SDA, during which time, an acknowledge clock pulse is generated by the slave device. If the LM49200 receives the correct address, the device pulls the SDA line low, generating an acknowledge bit (ACK).

Once the master device registers the ACK bit, the 8-bit register data word is sent. Each data bit should be stable while SCL is HIGH. After the 8-bit register data word is sent, the LM49200 sends another ACK bit. Following the acknowledgement of the register data word, the master issues a STOP bit, allowing SDA to go high while SCL is high.

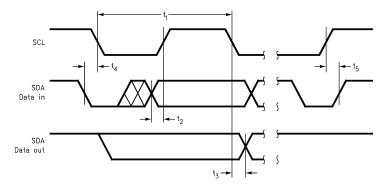


Figure 32. I<sup>2</sup>C Timing Diagram

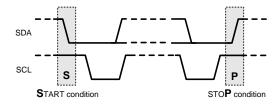


Figure 33. Start and Stop Diagram



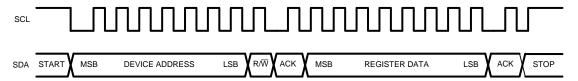


Figure 34. Start and Stop Diagram

# **Table 1. Chip Address**

	A7	A6	A5	A4	А3	A2	A1	A0
Chip Address	1	1	1	1	1	0	0	0

# Table 2. Control Registers<sup>(1)</sup>

Register	D7	D6	D5	D4	D3	D2	D1	D0
Shutdown Control	0	0	0	HPR_SD <sup>(2)</sup>	0	I <sup>2</sup> CV <sub>DD</sub> _SD <sup>(3)</sup>	Turn_On _Time(4)	Power_On <sup>(5)</sup>
Output Mode Control	0	1	0	EP_Mode <sup>(6)</sup> Mode_Control <sup>(7)</sup>				
Headphone Output Gain Control	1	0	0	0 0 HP_Gain <sup>(8)</sup>				
Mono Input Volume Control	1	0	1	Mono_Vol <sup>(9)</sup>				
Left Input Volume Control	1	1	0	Left_Vol <sup>(9)</sup>				
Right Input Volume Control	1	1	1	Right_Vol <sup>(9)</sup>				

- Notes: All registers default to 0 on initial power-up.
- HPR\_SD: Right channel shutdown control. See Table 3.

  I<sup>2</sup>CV<sub>DD</sub>\_SD: Control Enable Function. I<sup>2</sup>CV<sub>DD</sub> can be used to act as a hardware reset input. See Table 3. (3)
- Turn\_On\_Time: Reduces the turn on time for faster activation. See Table 3.
- Power\_On: Master Power on bit. See Table 3.
- EP\_Mode: EP (Receiver) Mode control. Right loudspeaker channel can be used as earpiece path. See Table 4.
- Mode\_Control: Sets the output mode. See Table 4.
- HP\_Gain: Sets the headphone amplifier output gain. See Table 5
- Mono\_Vol/Left\_Vol/Right\_Vol: Sets the input volume for Mono, Left and Right inputs. See Table 6.

#### **Table 3. Shutdown Control Register**

Bit	Name	Value	Description		
		This bit is a maste	er shutdown control bit and sets the device to be on or off.		
0	Power On	Value	Status		
U	Fower_On	0	Master power off, device disable.		
		1	Master power on, device enable.		
		This bit sets the to	urn on time of the device.		
1	Turn_On_Time	Value	Status		
1	Tuni_On_Time	0	Normal Turn-on time		
		1	Fast Turn-on time		
		This bit allows the I <sup>2</sup> C supply voltage to be used as a reset signal.			
		Value	Status		
2	I <sup>2</sup> CV <sub>DD</sub> _SD	0	I <sup>2</sup> CV <sub>DD</sub> acts as an active low reset input. If I <sup>2</sup> CV <sub>DD</sub> drops below 1.1V, the device resets and the I <sup>2</sup> C registers are restored to their default state.		
		1	Normal Operation. I <sup>2</sup> CV <sub>DD</sub> voltage does not reset the device.		
		This bit is used wi	nen only one channel of the headphone amplifier is needed.		
4	HPR_SD	0	Normal headphone operation.		
		1	Mono headphone output at left channel, right headphone in shutdown.		

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# Table 4. Output Mode Control Register<sup>(1)</sup>

Bits	Field		Description										
3:0	Mode_Control	These bits	s determin	e how the input sign	als are mixed and ro	uted to the outputs.							
		Value	Mode	Left Loudspeaker	Right Loudspeaker	Left Headphone	Right Headphone						
			0	SD SD SD			SD						
		0001	1	G <sub>M</sub> x M	G <sub>M</sub> x M	Mute	Mute						
		0010	2	G <sub>L</sub> x L	G <sub>L</sub> x L	Mute	Mute						
		011	3	G <sub>L</sub> x L + G <sub>M</sub> x M	G <sub>R</sub> x R + G <sub>M</sub> x M	Mute	Mute						
		0100	4	SD	SD	G <sub>M</sub> x M/2	G <sub>M</sub> x M/2						
		0101	5	G <sub>M</sub> x M	G <sub>M</sub> x M	G <sub>M</sub> x M/2	$G_{M} \times M/2$ $G_{M} \times M/2$ $G_{M} \times M/2$						
		0110	6	G <sub>L</sub> x L	G <sub>R</sub> x R	G <sub>M</sub> x M/2							
		0111	7	G <sub>L</sub> x L + G <sub>M</sub> x M	$G_L \times L + G_M \times M$	G <sub>M</sub> x M/2							
		1000	8	SD	SD	G <sub>L</sub> x L	G <sub>R</sub> x R						
		1001	9	G <sub>M</sub> x M	G <sub>M</sub> x M	G <sub>L</sub> x L	G <sub>R</sub> x R						
		1010	10	G <sub>L</sub> x L	G <sub>R</sub> x R	$G_L \times L$	G <sub>R</sub> x R						
		1011	11	G <sub>L</sub> x L + G <sub>M</sub> x M	$G_R \times R + G_M \times M$	G <sub>L</sub> x L	G <sub>R</sub> x R						
		1100	12	SD	SD	$G_L \times L + G_M \times M/2$	$G_R \times R + G_M \times M/2$						
		1101	13	G <sub>M</sub> x M	G <sub>M</sub> x M	$G_L \times L + G_M \times M/2$	$G_R \times R + G_M \times M/2$						
		1110	14	G <sub>L</sub> x L	G <sub>R</sub> x R	$G_L \times L + G_M \times M/2$	$G_R \times R + G_M \times M/2$						
		1111	15	G <sub>L</sub> x L + G <sub>M</sub> x M	$G_R \times R + G_M \times M$	$G_L \times L + G_M \times M/2$	$G_R \times R + G_M \times M/2$						
4	EP Mode	This bit se	ets the lou	dspeaker amplifiers	for earpiece mode.								
		Value			S	tatus							
		0	Normal I	oudspeaker operatio	on, control determine	d by bits 3:0.							
		1	Bit overrides bits 3:0. Right loudspeaker amplifier bias current reduced for low power operation. Left loudspeaker amplifier shutdown. Mono input path active and signal routed to right loudspeaker output. Left & right input gain amplifiers shutdown for reduced power consumption.										

(1) M: MIN, Mono differential input

L : LIN, Left single-ended input

R: RIN, Right single-ended input SD: Shutdown

 $G_M$ : Mono\_Vol setting determined by the Mono Input Volume Control register, See Table 6.  $G_L$ : Left\_Vol setting determined by the Left Input Volume Control register, See Table 6.

GR: Right\_Vol setting determined by the Right Input Volume Control register, See Table 6.

# **Table 5. Output Gain Control Register**

Bits	Field		Description				
2:0	HP_GAIN	These bits set the gain of the headphone output amplifiers.					
		Value	Gain (dB)				
		000	0				
		001	-1.2				
		010	-2.5				
		011	-4.0				
		100	-6.0				
		101	-8.5				
		110	-12				
		111	-18				



**Table 6. Input Volume Control Registers** 

Bits	Fields	Description							
4:0	Mono_Vol	These bits set the input volume for each input volume register listed.							
	Right_Vol Left_Vol	Volume Step	Value	Gain (dB)					
	LCIT_VOI	1	00000	-80.0					
		2	00001	-46.5					
		3	00010	-40.5					
		4	00011	-34.5					
		5	00100	-30.0					
		6	00101	-27.0					
		7	00110	-24.0					
		8	00111	-21.0					
		9	01000	-18.0					
		10	01001	-15.0					
		11	01010	-13.5					
		12	01011	-12.0					
		13	01100	-10.5					
		14	01101	-9.0					
		15	01110	-7.5					
		16	01111	-6.0					
		17	10000	-4.5					
		18	10001	-3.0					
		19	10010	-1.5					
		20	10011	0.0					
		21	10100	1.5					
		22	10101	3.0					
		23	10110	4.5					
		24	10111	6.0					
		25	11000	7.5					
		26	11001	9.0					
		27	11010	10.5					
		28	11011	12.0					
		29	11100	13.5					
		30	11101	15.0					
		31	11110	16.5					
		32	11111	18.0					

#### TURN\_ON\_TIME BIT

The Turn\_On\_Time bit determines the delay time from the Power\_On bit set to '1' and the internal circuits ready. For input capacitor values up to  $0.47\mu F$  the Turn\_On\_Time bit can be set to fast mode by setting the bit to a '1'. When the input capacitor values are larger than  $0.47\mu F$  then the Turn\_On\_Time bit should be set to '0' for normal turn-on time and higher delay. This allows sufficient time to charge the input capacitors to the  $\frac{1}{2}$  V<sub>DD</sub>LS bias voltage.

#### **POWER ON BIT**

The Power\_On bit is the master control bit to activate or deactivate the LM49200. All registers can be loaded independent of the Power\_On bit setting as long as the IC is powered correctly. Cycling the Power\_On bit does not change the values of any registers nor return all bits to the default power on value of zero. The Power\_On bit only determines whether the IC is on or off.



#### HPR SD BIT

The HPR\_SD bit will deactivate the right headphone output amplifier. This bit is provided to reduce power consumption when only one headphone output is needed.

#### **MODE CONTROL BITS**

In the LM49200 OUTPUT MODE CONTROL register (Table 4), Bit B5 (EP Bypass) controls the operation of the Earpiece Bypass path. If EP Bypass = 0, it would act under normal output mode operation set by bits B3, B2, B1, and B0. If EP Bypass = 1, it overrides the B3, B2, B1, and B0 Bits and enables the Receiver Bypass path, a class AB amplifier, to the speaker output.

Bit B4 (HPR\_SD) of the OUPUT MODE CONTROL register controls the right headphone shutdown. If HPR\_SD = 1, the right headphone output is disabled.

The LM49200 includes a comprehensive mixer multiplexer controlled through the I<sup>2</sup>C interface. The mixer/multiplexer allows any input combination to appear on any output of LM49200. Multiple input paths can be selected simultaneously. Under these conditions, the selected inputs are mixed together and output on the selected channel. Table 5 shows how the input signals are mixed together for each possible input selection.

#### **HP GAIN BITS**

The headphone outputs have an additional, single volume control set by the three HP\_Gain bits in the Output Gain Control register. The HP\_Gain volume setting controls the output level for both the left and the right headphone outputs.

#### LS (EP MODE) BIT

The LS (EP\_Mode) bit selects the amount of bias current in the loudspeaker amplifier. Setting the LS (EP\_Mode) bit to a '1' will reduce the amount of current from the V<sub>DD</sub>LS supply by approximately 0.5mA. The THD performance of the loudspeaker amplifier will be reduced as a result of lower bias current. See the performance graphs in Typical Performance Characteristics above.

#### **VOLUME CONTROL BITS**

The LM49200 has three independent 32-step volume controls, one for each of the inputs. The five bits of the Volume Control registers sets the volume for the specified input channel.

#### SHUTDOWN FUNCTION

The LM49200 features the following shutdown controls.

Bit B4 (GAMP\_SD) of the SHUTDOWN CONTROL register controls the gain amplifiers. When GAMP\_SD = 1, it disables the gain amplifiers that are not in use. For example, in Modes 1, 4 and 5, the Mono inputs are in use, so the Left and Right input gain amplifiers are disabled, causing the  $I_{DD}$  to be minimized.

Bit B0 (PWR\_On) of the SHUTDOWN CONTROL register is the global shutdown control for the entire device. Set PWR On = 0 for normal operation. PWR On = 1 overrides any other shutdown control bit.

#### **DIFFERENTIAL AMPLIFIER EXPLANATION**

The LM49200 features a differential input stage, which offers improved noise rejection compared to a single-ended input amplifier. Because a differential input amplifier amplifies the difference between the two input signals, any component common to both signals is cancelled. An additional benefit of the differential input structure is the possible elimination of the DC input blocking capacitors. Since the DC component is common to both inputs, and thus cancelled by the amplifier, the LM49200 can be used without input coupling capacitors when configured with a differential input signal.

#### **BRIDGE CONFIGURATION EXPLAINED**

By driving the load differentially through the MONO outputs, an amplifier configuration commonly referred to as "bridged mode" is established. Bridged mode operation is different from the classical single-ended amplifier configuration where one side of the load is connected to ground.

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A bridge amplifier design has a few distinct advantages over the single-ended configuration, as it provides differential drive to the load, thus doubling output swing for a specified supply voltage. Four times the output power is possible as compared to a single-ended amplifier under the same conditions. This increase in attainable output power assumes that the amplifier is not current limited or clipped.

A bridge configuration, such as the one used in LM49200, also creates a second advantage over single-ended amplifiers. Since the differential outputs are biased at half-supply, no net DC voltage exists across the load. This eliminates the need for an output coupling capacitor which is required in a single supply, single-ended amplifier configuration. Without an output coupling capacitor, the half-supply bias across the load would result in both increased internal IC power dissipation and also possible loudspeaker damage.

#### POWER DISSIPATION

Power dissipation is a major concern when designing a successful amplifier, whether the amplifier is bridged or single-ended. A direct consequence of the increased power delivered to the load by a bridge amplifier is an increase in internal power dissipation. The power dissipation of the LM49200 varies with the mode selected. The maximum power dissipation occurs in modes where all inputs and outputs are active (Modes 6, 7, 8, 9, 10, 11, 13, 14, 15). The power dissipation is dominated by the Class AB amplifier. The maximum power dissipation for a given application can be derived from the power dissipation graphs or from Equation 1.

$$P_{DMAX} = 4^* (V_{DD})^2 / (2\pi^2 R_L)$$
 (1)

It is critical that the maximum junction temperature (T<sub>JMAX</sub>) of 150°C is not exceeded. T<sub>JMAX</sub> can be determined from the power derating curves by using P<sub>DMAX</sub> and the PC board foil area. By adding additional copper foil, the thermal resistance of the application can be reduced from the free air value, resulting in higher P<sub>DMAX</sub>. Additional copper foil can be added to any of the leads connected to the LM49200. It is especially effective when connected to V<sub>DD</sub>, GND, and the output pins. Refer to the application information on the LM49200 reference design board for an example of good heat sinking. If T<sub>JMAX</sub> still exceeds 150°C, then additional changes must be made. These changes can include reduced supply voltage, higher load impedance, or reduced ambient temperature. Internal power dissipation is a function of output power. Refer to the curves in Typical Performance Characteristics for power dissipation information for different output powers and output loading.

#### POWER SUPPLY BYPASSING

As with any amplifier, proper supply bypassing is critical for low noise performance and high power supply rejection. The capacitor location on both the bypass and power supply pins should be as close to the device as possible. Typical applications employ a 5V regulator with 10µF tantalum or electrolytic capacitor and a ceramic bypass capacitor which aid in supply stability. This does not eliminate the need for bypassing the supply nodes of the LM49200. The selection of a bypass capacitor, especially C<sub>B</sub>, is dependent upon PSRR requirements, click and pop performance, system cost, and size constraints.

#### **GROUND REFERENCED HEADPHONE AMPLIFIER**

The LM49200 features a low noise inverting charge pump that generates an internal negative supply voltage. This allows the headphone outputs to be biased about GND instead of a nominal DC voltage, like traditional headphone amplifiers. Because there is no DC component, the large DC blocking capacitors (typically 220µF) are not necessary. The coupling capacitors are replaced by two small ceramic charge pump capacitors, saving board space and cost. Eliminating the output coupling capacitors also improves low frequency response. In traditional headphone amplifiers, the headphone impedance and the output capacitor from a high-pass filter that not only blocks the DC component of the output, but also attenuates low frequencies, impacting the bass response. Because the LM49200 does not require the output coupling capacitors, the low frequency response of the device is not degraded by external components. In addition to eliminating the output coupling capacitors, the ground referenced output nearly doubles the available dynamic range of the LM49200 headphone amplifiers when compared to a traditional headphone amplifier operating from the same supply voltage.



#### INPUT CAPACITOR SELECTION

Input capacitors may be required for some applications, or when the audio source is single-ended. Input capacitors block the DC component of the audio signal, eliminating any conflict between the DC component of the audio source and the bias voltage of the LM49200. The input capacitors create a high-pass filter with the input resistors R<sub>IN</sub>. The -3dB point of the high-pass filter is found using equation below.

$$f = 1 / 2\pi R_{IN}C_{IN}$$
 (Hz)

where

• the value of R<sub>IN</sub> is given in the Electrical Characteristics Table.

(2)

High-pass filtering the audio signal helps protect the speakers. When the LM49200 is using a single-ended source, power supply noise on the ground is seen as an input signal. Setting the high-pass filter point above the power supply noise frequencies, 217Hz in a GSM phone, for example, filters out the noise such that it is not amplified and heard on the output. Capacitors with a tolerance of 10% or better are recommended for impedance matching and improved CMRR and PSRR.

# CHARGE PUMP FLYING CAPACITOR (C<sub>1</sub>)

The flying capacitor (C1), see Figure 1, affects the load regulation and output impedance of the charge pump. A C1 value that is too low results in a loss of current drive, leading to a loss of amplifier headroom. A higher valued C1 improves load regulation and lowers charge pump output impedance to an extent. Above 2.2µF, the R<sub>DS(ON)</sub> of the charge pump switches and the ESR of C1 and Cs5 dominate the output impedance. A lower value capacitor can be used in systems with low maximum output power requirements.

#### CHARGE PUMP HOLD CAPACITOR (C<sub>S3</sub>)

The value and ESR of the hold capacitor (Cs5) directly affects the ripple on CPV<sub>SS</sub>. Increasing the value of Cs5 reduces output ripple. Decreasing the ESR of Cs5 reduces both output ripple and charge pump output impedance. A lower value capacitor can be used in systems with low maximum output power requirements.

Product Folder Links: LM49200 LM49200TLEVAL



#### **Demo Board Circuit**

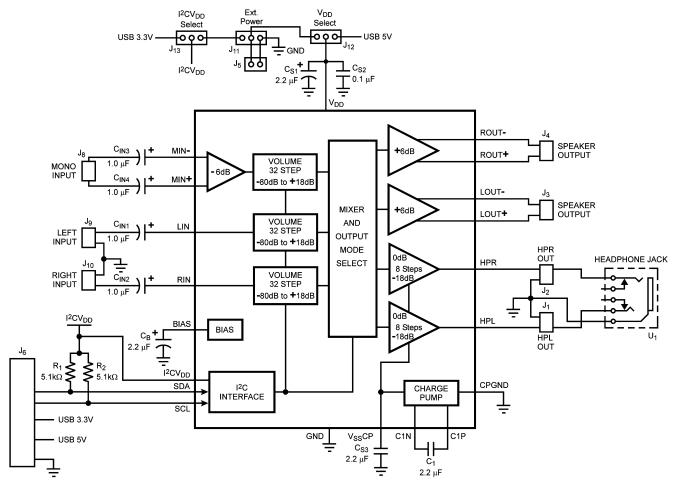


Figure 35. Demo Board Circuit

#### **Demonstration Board**

The demonstration board (see Figure 35) has connection and jumper options to be powered from the USB bus, from external power supplies or a combination of both. Additional options are to power  $I^2CV_{DD}$  and  $V_{DD}$  from a single power supply or separate power supplies, as long as the voltage limits for each power supply are not exceeded. See the Operating Ratings for each supply's limit range. When powered from the USB bus the  $I^2CV_{DD}$  will be set to 3.3V and the  $V_{DD}$  will be set to 5V. Jumper headers J13 and J12 must be set accordingly. If a single power supply for  $I^2CV_{DD}$  and  $V_{DD}$  is desired then header J5 should be used with a jumper added to header J11 to connect  $I2CV_{DD}$  to the external supply voltage connected to J5.

Connection headers J1 and J2 are provided along with the stereo headphone jack J4 for easily connection and monitoring of the headphone outputs.



#### LM49200 microSMD Demo Board Views

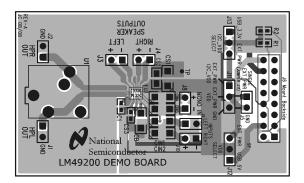


Figure 36. Composite View

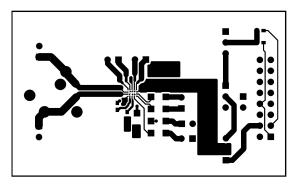


Figure 38. Top Layer

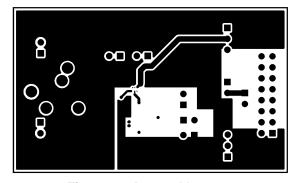


Figure 40. Internal Layer 2

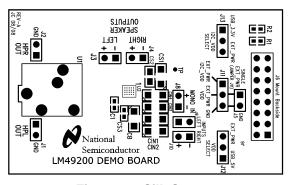


Figure 37. Silk Screen

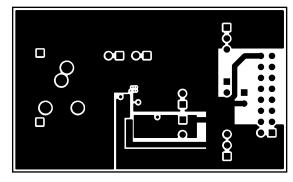


Figure 39. Internal Layer 1

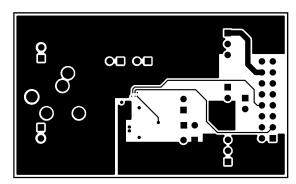


Figure 41. Bottom Layer



#### LM49200 Reference Demo Board Bill Of Materials

#### Table 7. Bill Of Materials

Designator	Vlaue	Tolerance	Part Description	Comment
$R_1, R_2$	5.1kΩ	5%	1/10W, 0603 Resistors	
$\begin{array}{c} C_{IN1},C_{IN2} \\ C_{IN3},C_{IN4} \end{array}$	1µF	10%	1206, X7R Ceramic Capacitor	
$C_{S1}, C_{B}$	2.2µF	10%	Size A, Tantalum Capacitor	
C <sub>S2</sub>	0.1µF	10%	0805, 16V, X7R Ceramic Capacitor	
C <sub>S3</sub> , C <sub>1</sub>	2.2µF	10%	0603, 10V, X7R Ceramic Capacitor	
U <sub>2</sub>			LM49200TL	
J <sub>1</sub> , J <sub>2</sub> , J <sub>3</sub> J <sub>4</sub> , J <sub>5</sub> , J <sub>8</sub> J <sub>9</sub> , J <sub>10</sub>			0.100" 1x2 header, vertical mount	Input, Output, V <sub>DD</sub> , GND
J <sub>11</sub> , J <sub>12</sub> , J <sub>13</sub>			0.100" 1x3 header, vertical mount	V <sub>DD</sub> Selects, V <sub>DD</sub> , I <sup>2</sup> CV <sub>DD</sub> , GND
J <sub>6</sub>			16 pin header	I <sup>2</sup> C Connector
U <sub>1</sub>			Headphone Jack	

# **PCB Layout Guidelines**

This section provides practical guidelines for mixed signal PCB layout that involves various digital/analog power and ground traces. Designers should note that these are only "rule-of-thumb" recommendations and the actual results will depend heavily on the final layout.

#### **General Mixed Signal Layout Recommendations**

#### SINGLE-POINT POWER AND GROUND CONNECTIONS

The analog power traces should be connected to the digital traces through a single point (link). A "Pi-filter" can be helpful in minimizing high frequency noise coupling between the analog and digital sections. It is further recommended to put digital and analog power traces over the corresponding digital and analog ground traces to minimize noise coupling.

#### PLACEMENT OF DIGITAL AND ANALOG COMPONENTS

All digital components and high-speed digital signals traces should be located as far away as possible from analog components and circuit traces.

#### AVOIDING TYPICAL DESIGN AND LAYOUT PROBLEMS

Avoid ground loops or running digital and analog traces parallel to each other (side-by-side) on the same PCB layer. When traces must cross over each other do it at 90 degrees. Running digital and analog traces at 90 degrees to each other from the top to the bottom side as much as possible will minimize capacitive noise coupling and cross talk.

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# SNAS459A -MAY 2009-REVISED APRIL 2013



# **REVISION HISTORY**

Rev	Date	Description
1.0	05/21/09	Initial release.
Α	04/08/2013	Changed layout of National Data Sheet to TI format.

www.ti.com 23-May-2025

#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
LM49200TL/NOPB	Active	Production	DSBGA (YZR)   20	250   SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	GL3
LM49200TL/NOPB.A	Active	Production	DSBGA (YZR)   20	250   SMALL T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	GL3
LM49200TLX/NOPB	Active	Production	DSBGA (YZR)   20	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	GL3
LM49200TLX/NOPB.A	Active	Production	DSBGA (YZR)   20	3000   LARGE T&R	Yes	SNAGCU	Level-1-260C-UNLIM	-40 to 85	GL3

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(2)</sup> Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

<sup>(4)</sup> Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

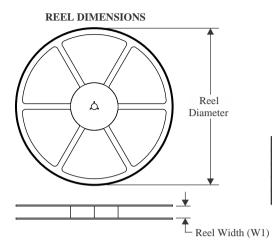
<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

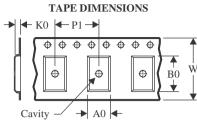
<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

# **PACKAGE MATERIALS INFORMATION**

www.ti.com 1-Nov-2025

# TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

#### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM49200TL/NOPB	DSBGA	YZR	20	250	178.0	8.4	2.18	2.69	0.76	4.0	8.0	Q1
LM49200TLX/NOPB	DSBGA	YZR	20	3000	178.0	8.4	2.18	2.69	0.76	4.0	8.0	Q1

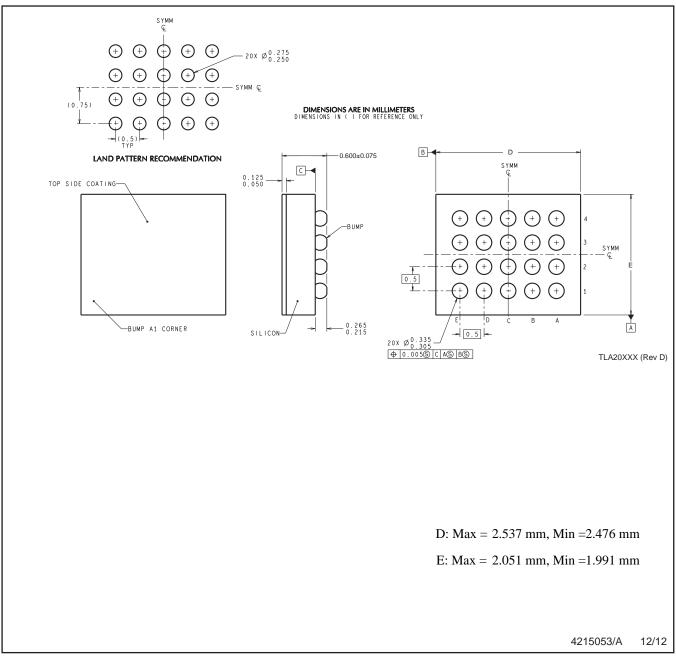
# **PACKAGE MATERIALS INFORMATION**

www.ti.com 1-Nov-2025



#### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM49200TL/NOPB	DSBGA	YZR	20	250	208.0	191.0	35.0
LM49200TLX/NOPB	DSBGA	YZR	20	3000	208.0	191.0	35.0



NOTES: A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.

B. This drawing is subject to change without notice.

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